

17648 U.S. PTO  
110403

Attorney Docket No. 2271/71390  
Total Pages 3  
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**Mail Stop Patent Application**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

17510 U.S. PTO  
10/701061  
11/04/03

Transmitted herewith for filing under 37 CFR 1.53(b) are the specification and claims of the nonprovisional patent application of:

Hitoshi Arita and Akio Kojima  
Inventor(s)

SOLDER ALLOY MATERIAL LAYER COMPOSITION, ELECTROCONDUCTIVE AND ADHESIVE  
COMPOSITION, FLUX MATERIAL LAYER COMPOSITION, SOLDER BALL TRANSFERRING SHEET,  
BUMP AND BUMP FORMING PROCESS, AND SEMICONDUCTOR DEVICE

Title of Invention

APPLICATION ELEMENTS ENCLOSED:

1. X Specification, total pages 190 including:
  - a. 21 pages of claims (54 claims)
  - b. 1 page(s) Abstract
2. X 13 sheets of      informal X formal drawings (Figs. 1-23)
3.      Oath or declaration of Applicant(s) (5 total pages)
  - a.      Newly executed (original)
  - b.      Unexecuted
  - c.      Copy from a prior application (37 CFR 1.63(d))  
(for continuation/divisional with Item 14 completed)
4.      Deletion of Inventor(s)  
Signed statement attached deleting inventor(s) named in the prior application, see 37 CFR 1.63(d)(2) and 1.33(b)
5.      Incorporation By Reference  
The entire disclosure of the prior application, from which a copy of the oath or declaration is supplied in item 3b is considered as being part of the disclosure of the accompanying application and is hereby incorporated by reference therein.
6.      Microfiche Computer Program (Appendix)

APPLICATION PARTS ENCLOSED:

7.      An assignment (cover sheet & document(s))
8.      37 CFR 3.73(b) Statement (when there is an assignee)
9.      Power of Attorney
  - a.      Newly executed (original)
  - b.      Unexecuted
  - c.      Copy from a prior application

10. \_\_\_ Information Disclosure Statement (IDS) and PTO-1449  
     \_\_\_ Copies of IDS Citations
11. \_\_\_ A Preliminary Amendment
12. X Return Receipt Postcard (MPEP 503)
13. \_\_\_ Applicant(s) hereby establish small entity status under 37 C.F.R. §1.9 and §1.27
14. \_\_\_ If a Continuing Application, *check the appropriate box and supply the requisite information:*

☐ Continuation of prior application No.: \_\_\_\_\_ filed \_\_\_\_\_

☐ Divisional of prior application No.: \_\_\_\_\_ filed \_\_\_\_\_


☐ Continuation-in-part (CIP) of prior application No.: \_\_\_\_\_ filed \_\_\_\_\_

15. \_\_\_ Amend the specification by inserting before the first line of page one: --This is a \_\_\_ continuation \_\_\_ divisional of application Serial No. \_\_\_\_\_ filed \_\_\_\_--
16. X Applicant hereby claim priority under 35 U.S.C. §119..  
     X Certified copies of priority applications No. 2002-322678, filed on November 6, 2002, in Japan, No. 2002-340384, filed on November 25, 2002, in Japan and No. 2002-342329, filed on November 26, 2002, in Japan are enclosed herewith.
17. X Other (identify) Express Mail Letter of Transmittal bearing Label No. EV 325707583 dated November 4, 2003

The filing fee is calculated as follows:

CLAIMS AS FILED, LESS ANY CLAIMS CANCELLED BY AMENDMENT

					Rate		Fee	
	Number Filed		Number Extra*		Small Entity	Other Entity	Small Entity	Other Entity
Total Claims	54 - 20	=	34	X	\$ 9	\$ 18	\$ 0	\$ 612.00
Indep. Claims	9 - 3	=	6	X	\$ 43	\$ 86	\$ 0	\$ 516.00
Multiple Dependent Claims Presented: Yes ___ No <u>x</u>					\$140	\$280	\$ 0	\$ 0.00
If the difference in column 1 is less than zero, enter "0" in column 2					Basic Fee		\$385.00	\$ 770.00
					Total Fee		\$	\$1,898.00

  
Paul Teng, Reg. No. 40,837  
Attorney for Applicants  
Cooper & Dunham LLP  
1185 Avenue of the Americas  
New York, New York 10036  
Tel.: (212) 278-0400

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants : Hitoshi Arita and Akio Kojima  
Serial No. : Not Yet Known  
Date Filed : Herewith  
Priority Date : November 6, 2002  
For : SOLDER ALLOY MATERIAL LAYER COMPOSITION,  
ELECTROCONDUCTIVE AND ADHESIVE COMPOSITION,  
FLUX MATERIAL LAYER COMPOSITION, SOLDER BALL  
TRANSFERRING SHEET, BUMP AND BUMP FORMING  
PROCESS, AND SEMICONDUCTOR DEVICE

**Mail Stop Patent Application**

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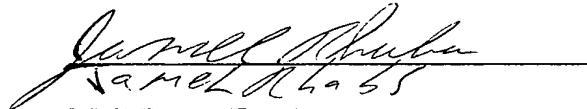
Sir:

**EXPRESS MAIL LETTER OF TRANSMITTAL**

Express Mail mailing label number: EV 325707583 US

Date of Deposit: November 4, 2003

I hereby certify that the above-identified application of Hitoshi Arita and Akio Kojima for SOLDER ALLOY MATERIAL LAYER COMPOSITION, ELECTROCONDUCTIVE AND ADHESIVE COMPOSITION, FLUX MATERIAL LAYER COMPOSITION, SOLDER BALL TRANSFERRING SHEET, BUMP AND BUMP FORMING PROCESS, AND SEMICONDUCTOR DEVICE, including application transmittal in triplicate, Specification (190 pages), Claims (1-54, 21 pages), Abstract (1 page), 13 drawing sheets (Figs. 1-23), Certified copies of JP 2002-322678, JP2002-340384, and JP2002-342329, a check in the Amount of \$1,898.00 for Filing Fee, and Return Postcard., is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR §1.10 on the date indicated above and is addressed to the Mail Stop Patent Application, Commissioner for Patents, P.O. Box 1450, Alexandria VA 22313-1450.



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Attorneys for Applicant:  
IVAN S. KAVRUKOV, Reg. No. 25,161  
PAUL TENG, Reg. No. 40,837  
Cooper & Dunham LLP  
1185 Avenue of the Americas  
New York, New York 10036  
Tel: (212) 278-0400